



SM2KxxCF Series Transient Voltage Suppressor

Rev.1.2

FEATURES:

- ✧ Excellent clamping capability.
- ✧ Low profile package and low inductance.
- ✧ High peak pulse voltage capability at 1.2/50 μ s-8/20 μ s@2 Ω waveform.
- ✧ Fast response time: typically less than 1.0ps from 0V to V_{BR} min.
- ✧ High temperature soldering: 260°C/40s at terminals.
- ✧ Plastic package has underwriters laboratory flammability 94V-0.
- ✧ Meets MSL level 1, per J-STD-020, LF maximum peak of 260°C.
- ✧ Terminal: solder plated, solderable per J-STD-002.
- ✧ For surface mounted applications in order to optimize board space.
- ✧ UL 1449 item recognized. (File No.: E494389).
- ✧ IEC61000-4-2 (ESD) \pm 30kV (air), \pm 30kV (contact).

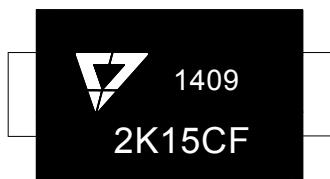


SMBF

Bi-directional
SymbolABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ\text{C}$, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Storage temperature range	T_{STG}	-55 to +150	°C
operating junction temperature range	T_J	-55 to +150	°C
Steady state power dissipation at $T_L=75^\circ\text{C}$	$P_{M(AV)}$	6.5	W
Peak pulse voltage at 1.2/50 μ s-8/20 μ s@2 Ω waveform	V_{PP}	4000	V

MARKING



2K15CF : Device Marking Code
1409: In ninth week, 2014

ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$)

Part Number	Marking Code	V_R	$I_R@V_R$	$V_{BR}@I_T$		I_T	$V_c@V_{PP}^{\text{(1)}}$	$V_{PP}^{\text{(1)}}$
Bi-Polar		V	max(μA)	min(V)	max(V)	mA	max(V)	V
SM2K15CF	2K15CF	15	1	16.7	18.5	1	42	4000
SM2K16CF	2K16CF	16	1	17.8	19.7	1	43	4000
SM2K18CF	2K18CF	18	1	20.0	22.3	1	45	4000
★SM2K20CF	2K20CF	20	1	22.0	24.5	1	47	4000

(1) Surge waveform: 1.2/50μs-8/20μs@2Ω

 V_R : Stand-off voltage -- Maximum voltage that can be applied V_{BR} : Breakdown voltage V_c : Clamping voltage -- Peak voltage measured across the suppressor at a specified V_{PP} I_R : Reverse leakage current

★: Products with negative resistance

ORDERING INFORMATION

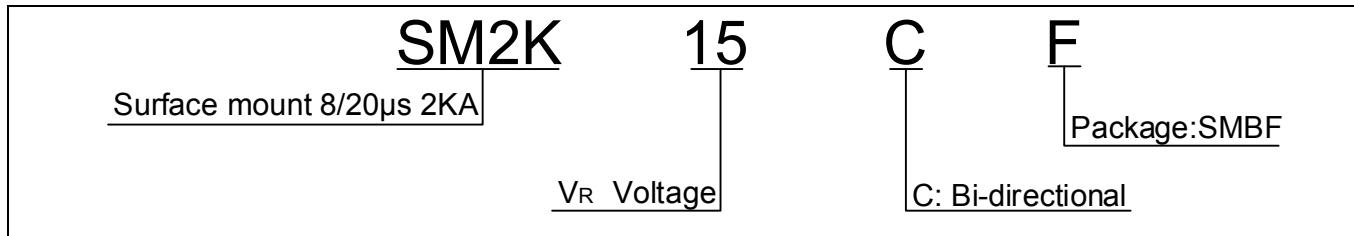
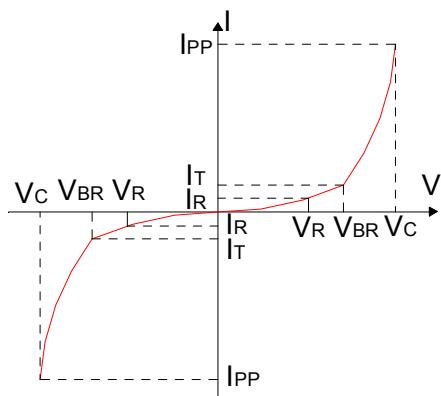
RATINGS AND V-I CHARACTERISTICS CURVES ($T_A=25^\circ\text{C}$, unless otherwise noted)FIG.1: V-I curve characteristics
(Bi-directional)

FIG.2: Pulse waveform

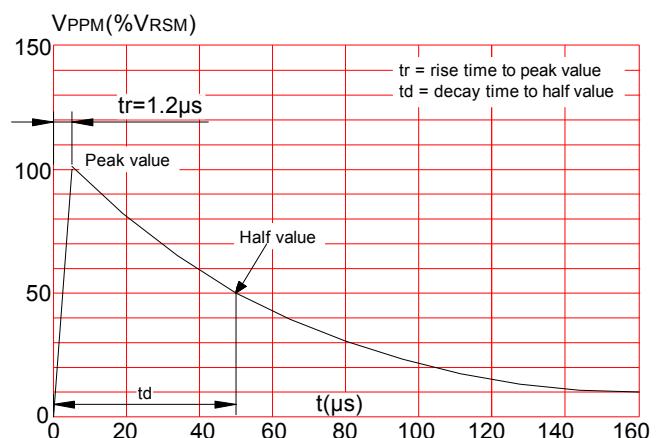
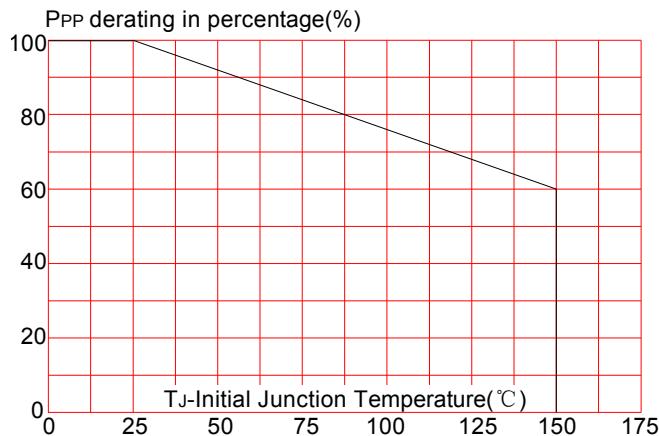
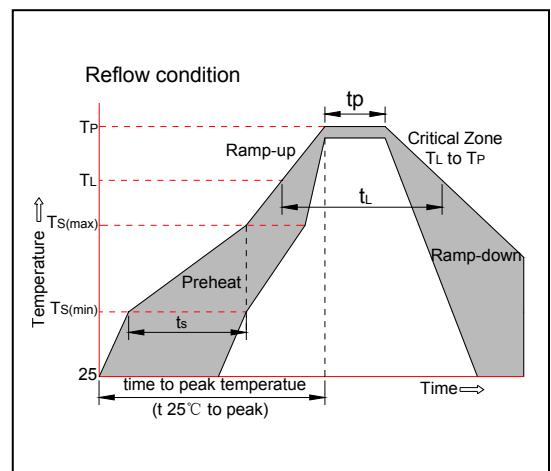


FIG.3: Pulse derating curve

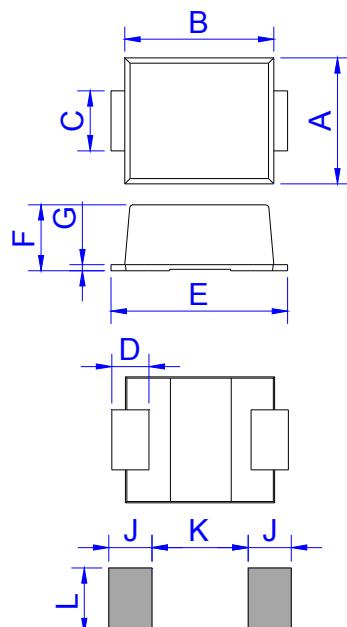


SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min (T _{s(min)})	+150°C
	-Temperature Max(T _{s(max)})	+200°C
	-Time (Min to Max) (t _s)	60-180 secs.
Average ramp up rate (Liquidus Temp (T _L)to peak)		3°C/sec. Max
T _{s(max)} to T _L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T _L)(Liquidus)	+217°C
	-Temperature(t _L)	60-150 secs.
Peak Temp (T _p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t _p)		20-40secs.
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T _P)		8 min. Max
Do not exceed		+260°C



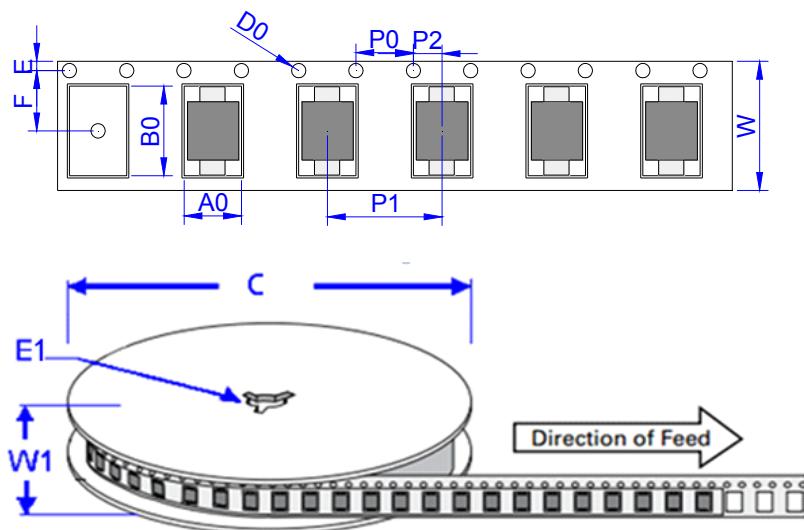
PACKAGE MECHANICAL DATA



SMBF

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	3.90	4.50	0.154	0.177
B	4.65	5.15	0.183	0.203
C	1.85	2.15	0.073	0.085
D	0.60		0.024	
E	5.60	6.00	0.220	0.236
F	2.05	2.35	0.081	0.093
G	0.12	0.28	0.005	0.011
J	2.00		0.079	
K		3.20		0.126
L	2.30		0.091	

TAPE AND REEL SPECIFICATION-SMBF



Ref.	Dimensions	
	Millimeters	Inches
A0	4.50±0.3	0.177 ± 0.012
B0	6.10±0.3	0.240 ± 0.012
C	330.0	13.0
D0	1.55±0.1	0.061 ± 0.004
E	1.75±0.2	0.069 ± 0.008
E1	13.3±0.3	0.524± 0.012
F	5.5±0.2	0.217 ± 0.008
P0	4.00±0.2	0.157 ± 0.008
P1	8.00±0.2	0.315 ± 0.008
P2	2.00±0.2	0.079 ± 0.008
W	12.0±0.2	0.472 ± 0.008
W1	15.7±2.0	0.618 ± 0.079

PART No.	UNIT WEIGHT (g/PCS) typ.	REEL (PCS)	PER CARTON (PCS)	DESCRIPTION
SM2KxxCF	0.13	3,000	48,000	13 inch reel pack

Information furnished in this document is believed to be accurate and reliable. However, Jiangsu JieJie Microelectronics Co.,Ltd assumes no responsibility for the consequences of use without consideration for such information nor use beyond it.

Information mentioned in this document is subject to change without notice, apart from that when an agreement is signed, Jiangsu JieJie complies with the agreement.

Products and information provided in this document have no infringement of patents. Jiangsu JieJie assumes no responsibility for any infringement of other rights of third parties which may result from the use of such products and information.

This document is the 1.2nd version which is made in 4-Aug.-2021. This document supersedes and replaces all information previously supplied.

 is a registered trademark of Jiangsu JieJie Microelectronics Co.,Ltd.

Copyright©2021 Jiangsu JieJie Microelectronics Co.,Ltd. Printed All rights reserved.